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# **Electronic Supplementary Material**

## Assessing the Fracture and Dynamic Mechanical Performance of CF/PEKK Joints Bonded with Epoxy-based Adhesive Film for Aerospace Applications: Impact of Thermal and Cycling Hygrothermal Conditions

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### SUPPLEMENTARY FIGURES



HT Conditioning

LT Conditioning

Supplementary Figure S1. HT and LT conditioning in the climatic chamber of INSTRON 5982 universal

testing machine.



Supplementary Figure S1. Stereo microscopy images of DCB specimens.



Supplementary Figure S2. SEM images of RT-conditioned DCB specimens.



Supplementary Figure S3. SEM images of HT-conditioned DCB specimens.



Supplementary Figure S4. SEM images of LT-conditioned DCB specimens.



Supplementary Figure S5. SEM images of CHT-conditioned DCB specimens.